

Title (en)

ELECTRONIC COMPONENT AND COATING AGENT

Title (de)

ELEKTRONISCHES BAUELEMENT UND BESCHICHTUNGS-MITTEL

Title (fr)

COMPOSANT ELECTRONIQUE ET AGENT DE REVETEMENT

Publication

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Application

**EP 00971253 A 20000921**

Priority

- DE 0003290 W 20000921
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Abstract (en)

[origin: WO0122501A1] The invention relates to an electronic component comprising, in predetermined areas, soldered regions that are arranged on at least one outer surface, whereby the component is coated on its surface that is not formed by the soldered regions with a layer that prevents the adherence of soldering agents thereto. The invention also relates to a coating agent for reducing the amount of solder tailings.

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IPC 8 full level

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CPC (source: EP KR)

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Citation (search report)

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